

IN THE CLAIMS:

Please amend the claims as follows:

1-4 (cancelled).

5 (currently amended). The method of claim 5, A method of manufacturing a plurality of MEMS devices comprising:

aligning a plurality of MEMS dice formed on a first substrate with a plurality of non-silicon caps having at least one electrical via; and

bonding the plurality of MEMS dice with the plurality of non-silicon caps to form a plurality of MEMS devices, the plurality of MEMS devices having an interior and an exterior, wherein the electrical via extends from the interior to the exterior,

wherein the bonding of the plurality of MEMS dice with the plurality of non-silicon caps is achieved by a thermocompression bonding.

6 (original). The method of claim 5, wherein the bonding of the plurality of MEMS dice with the plurality of non-silicon caps is achieved by a gold-to-gold thermocompression bonding.

7 (cancelled).

8 (currently amended). The method of claim 1 A method of manufacturing a plurality of MEMS devices comprising:

aligning a plurality of MEMS dice formed on a first substrate with a plurality of non-silicon caps having at least one electrical via; and

bonding the plurality of MEMS dice with the plurality of non-silicon caps to form a plurality of MEMS devices, the plurality of MEMS devices having an interior and an exterior, wherein the electrical via extends from the interior to the exterior,

wherein the bonding of the plurality of MEMS dice with the plurality of non-silicon caps is achieved by eutectic bonding.

9-12 (cancelled).

13 (currently amended). The apparatus of claim 11; An apparatus comprising:

a plurality of MEMS dice formed on a substrate; and

a plurality of caps bonded to the plurality of MEMS dice, the plurality of caps having at least one electrical via extending from a first side of the plurality of caps to a second side of the plurality of caps,

wherein one of the plurality of MEMS dice and one of the plurality of caps forms a device interior and a device exterior, and the electrical via extends from the device interior to the device exterior,

wherein the plurality of caps comprises ceramic and wherein the plurality of caps are coupled to each other by a carrier.

14 (currently amended). The apparatus of claim 40 13, wherein the electrical via is coupled to a solder ball on the device exterior.

15 (currently amended). The apparatus of claim An apparatus comprising:
a plurality of MEMS dice formed on a substrate; and
a plurality of caps bonded to the plurality of MEMS dice, the plurality
of caps having at least one electrical via extending from a first side of the
plurality of caps to a second side of the plurality of caps,
wherein one of the plurality of MEMS dice and one of the plurality of
caps forms a device interior and a device exterior, and the electrical via
extends from the device interior to the device exterior,
wherein the plurality of caps comprises a zero-shrink ceramic.

16 (currently amended). A apparatus comprising:
a MEMS die formed on a semiconductor substrate; and
a ceramic cap bonded to the MEMS die to form a hermetically sealed
interior, the ceramic cap having at least one electrical via extending from a
hermetically sealed interior through the ceramic cap to an exterior,
wherein the ceramic cap is a zero-shrink ceramic.

17 (original). The apparatus of claim 16, wherein the at least one electrical via is coupled to a solder ball on the exterior.

18 (original). The apparatus of claim 16 further comprising: a circuit board, wherein the circuit board is electrically coupled to the MEMS die by a solder ball and the electrical via.

19 (original). The apparatus of claim 16 further comprising:
an integrated circuit chip, wherein the integrated circuit chip is
electrically coupled to the MEMS die by a solder ball and the electrical via.

20 (cancelled).